Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTION:**

1. **QB**
2. **QC**
3. **QD**
4. **QE**
5. **QF**
6. **QG**
7. **QH**
8. **GND**
9. **QH**
10. **N. SRCLR**
11. **SRCLK**
12. **RCLK**
13. **N. OE**
14. **SER**
15. **QA**
16. **VCC**

**15**

**16**

**1**

**2**

**14 13 12 11**

**10**

**9**

**8**

**7**

**3 4 5 6**

**.030”**

**.041”**

**MHA595**

**MASK**

**REF**

**.MASK**

**REF**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size = .004 x .004”**

**Backside Potential: VCC or FLOAT**

**Mask Ref: MHA595**

**APPROVED BY: DK DIE SIZE .031” X .041” DATE: 8/26/21**

**MFG: SILICON SUPPLIES THICKNESS .014” P/N: 54HC595**

**DG 10.1.2**

#### Rev B, 7/1